

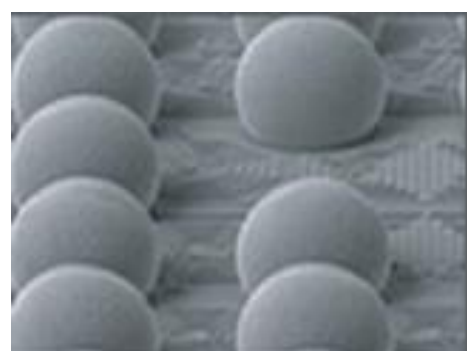


**可对应各种类型的凸块测试**  
Supports measurement of various bump types  
(Cu-pillar/Solder bump, Gold bump, and  $\mu$ -Bump)

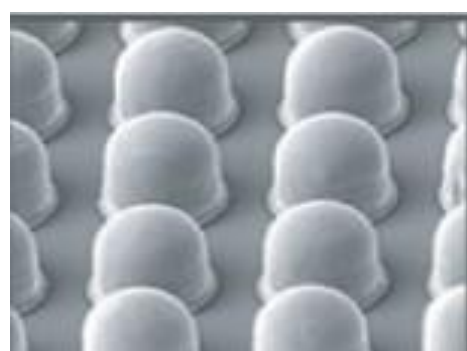
**2D/3D测定精度大幅提升**  
3D分解能: 2倍:  $2.8\ \mu\text{m}$  | 5倍:  $1.1\ \mu\text{m}$  | 10倍:  $0.6\ \mu\text{m}$ (Option)  
Significantly Enhanced 2D / 3D Measurement Accuracy

**可对应6/8/12英寸晶圆**  
Supports 6/8/12 inch Wafers

**可对应多种凸块结构，实现3D/2D/SD的高速高精度同步测量**  
Supports Various bump structures with high-speed, high-precision simultaneous 3D/2D/SD measurement



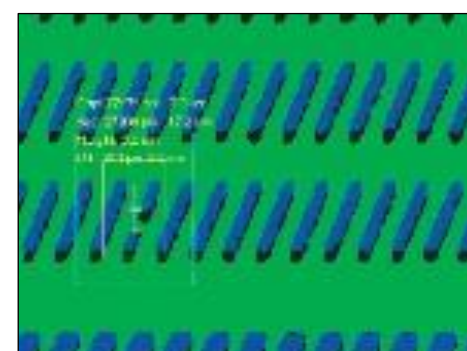
Solder bump



Cu pillar

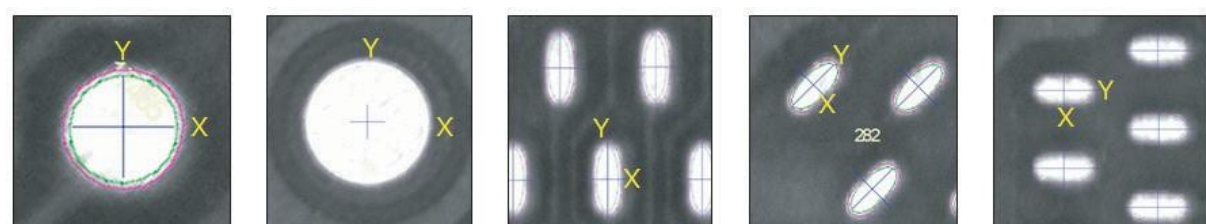


Gold bump

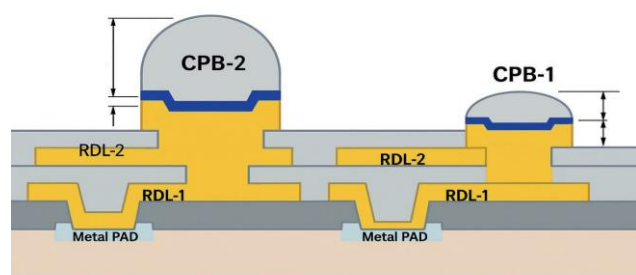
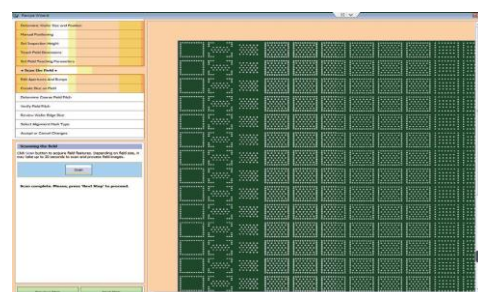


Inclined bump

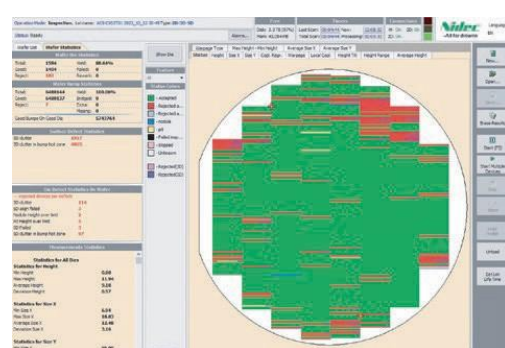
**适应不同凸起角度的测量**  
Supports measurement at different bump angles



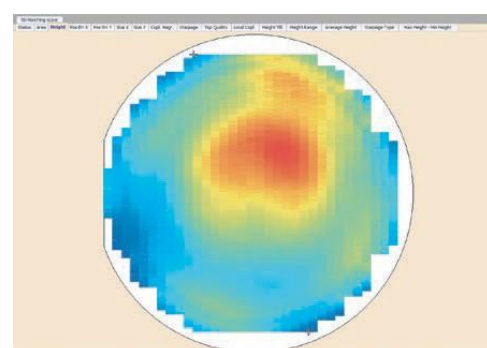
**一次扫描即可同时测量多个晶粒及凸起高度**  
Multi-Die and Multi-Bump Height Measurement in a Single Scan



**自动碰撞检测及高度映射结果**  
Automated Bump Inspection and Height Mapping Results

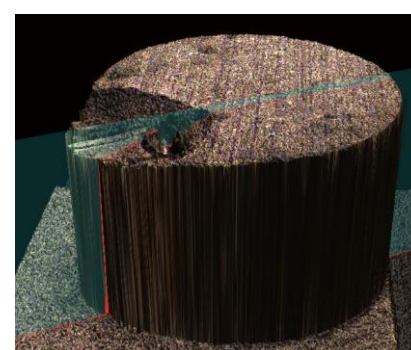


Defect/Yield Map

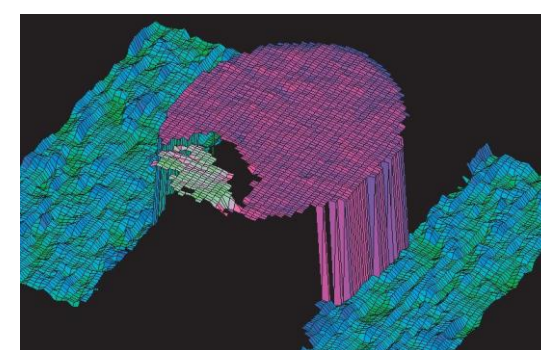


Height Topography Map

**根据凹凸贴图的3D信息，可生成3D像素级模型**  
Generates 3D pixel-level models based on bump 3D information

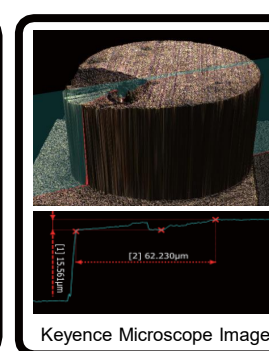
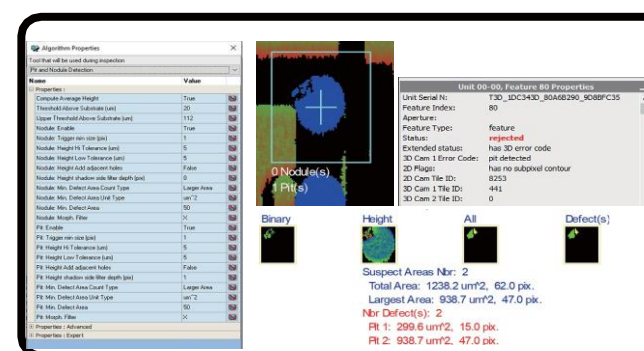


Microscope Image

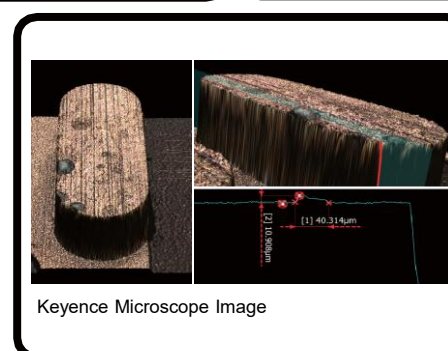
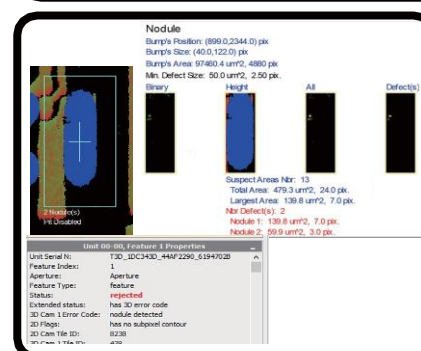


3D pixel-level model

**可测定凸块上方的凹坑和凹凸**  
Detects and measures pit / nodule defects on bump top surfaces



Pit Detection



Nodule Detection